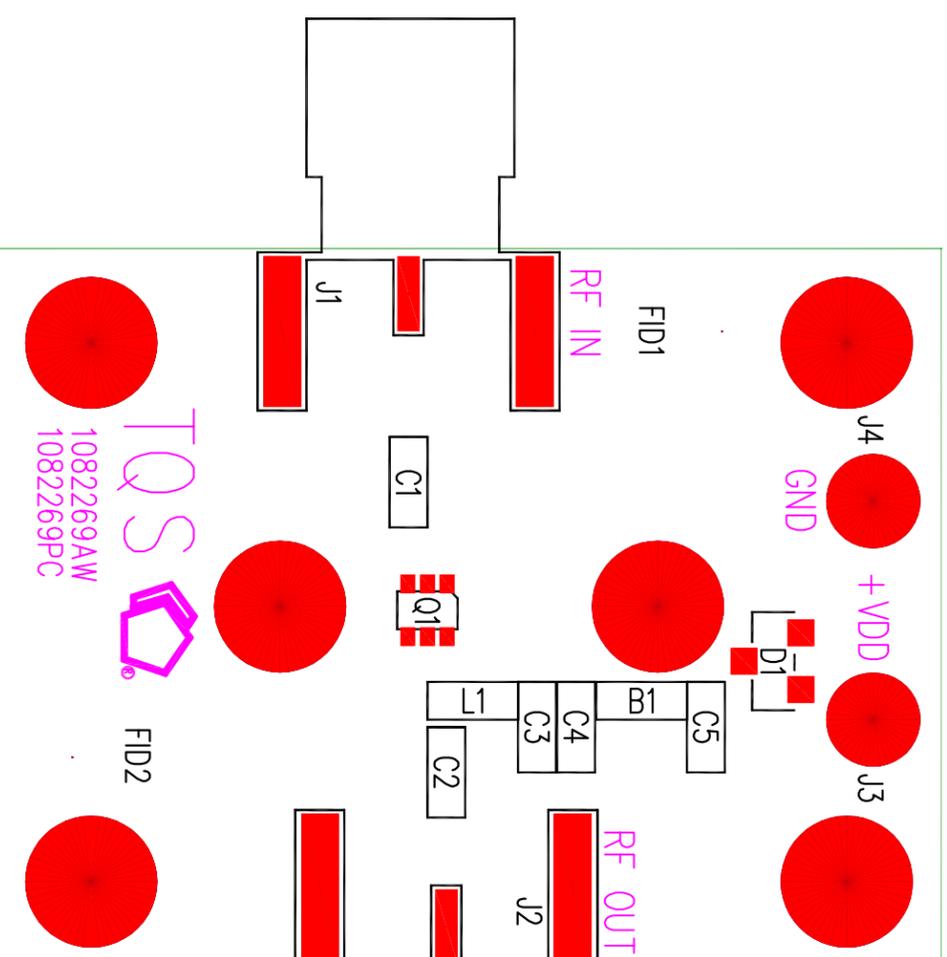


NOTES UNLESS OTHERWISE SPECIFIED:

1. ASSEMBLE IAW J-STD-001 CURRENT REVISION. THE ASSEMBLY IS TO MEET THE INSPECTION CRITERIA OF IPC-A-610, CLASS 2, CURRENT REVISION.
2. REFERENCE DOCUMENTS:  
SCHEMATIC DIAGRAM: 1082269SD.  
BILL OF MATERIAL: 1082269-001
3. THIS ASSEMBLY CONTAINS ELECTROSTATIC SENSITIVE DEVICES; HANDLE IAW MIL-STD-1686, CLASS 2.
4. SOLDER PASTE THICKNESS TO BE .006 ±.002.
5. CONVECTION HEATING ONLY IS TO BE USED DURING SOLDER REFLOW, NO IR.
6. BAG AND TAG (OR MARK CONTAINER) WITH PART NO. 1082269-001 AND CURRENT REV LEVEL.
7. VIAS ARE OMITTED FOR CLARITY.
8. PADS OF SMALL CHIP RESISTORS AND CAPACITORS ARE OMITTED FOR CLARITY.
9. AQUEDUS CLEANING IS REQUIRED.
10. NO-LOAD PARTS: ALL COMPONENTS WITH TRIQUINT PART NO. 445930-001. SEE BOM.
11. ASSEMBLY INSTRUCTIONS:  
-STEP 1:  
ASSEMBLE ALL SMD DEVICES.  
-STEP 2:  
INSTALL J1, J2, J3, AND J4.

TOP SIDE



QTY	PERS	BASE	NO	ITEM NO	PART IDENT NO	CAGE CODE	NDM/CAGE CODE	DESCRIPTION	SPEC/STD
PARTS LIST OR MATERIAL									

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES.  
 1X DEC. & .02 TYPICAL .63 MAX ANGLES ± 0° 30'  
 XXX DEC. & .005 V ± .02" P

MATERIAL	SR	K. KEISEN	6-6-11	CIRCUIT CARD ASSEMBLY SOT 363	SIZE D 14482	CAGE CODE 1082269	REV -
	CHK	C. BLUM	6-6-11				
FINAL PROTECTIVE FINISH	AFG						
	SA				SCALE	1.0	
	TR						
	CDR						

TRIQUINT SEMICONDUCTOR PROPRIETARY INFORMATION